

# EECS 151/251A

## SP2022 Discussion 6

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GSI: DIMA NIKIFOROV, YIKUAN CHEN

# Agenda

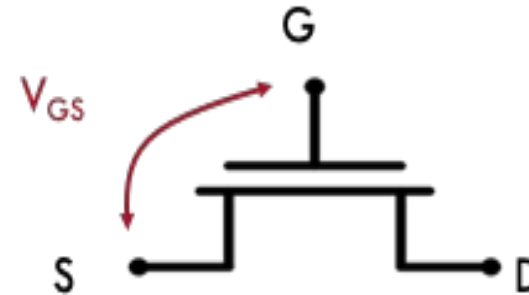
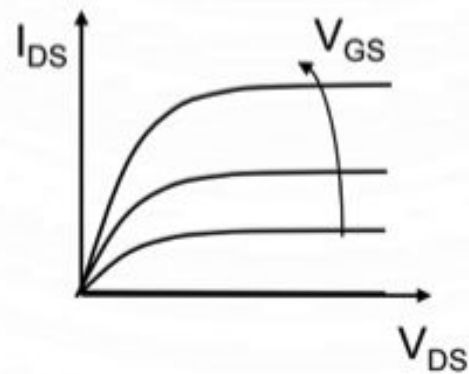
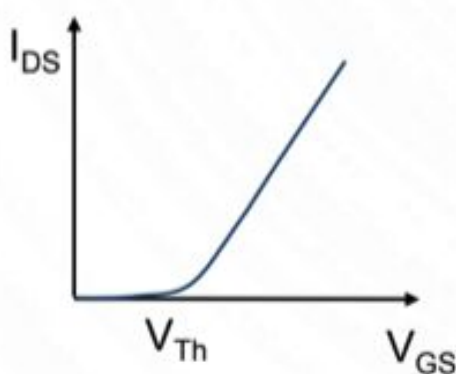
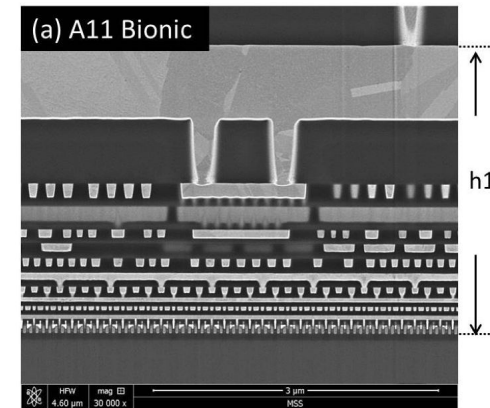
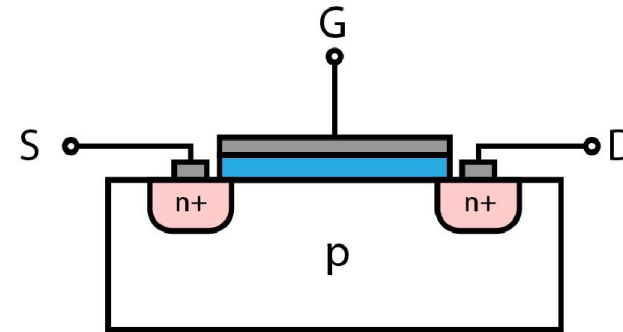
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- MOS
- CMOS
- Inverters/Inverter Chain

# MOS

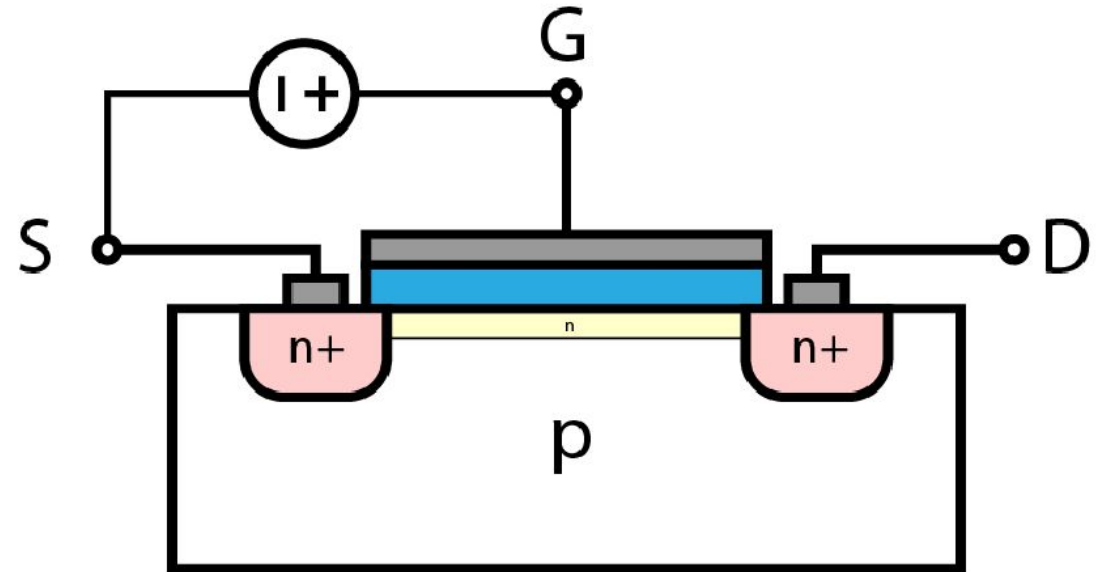
# Metal Oxide Semiconductor (MOS) Transistors

- Used to be made in a planar process
  - Wafer is usually p-doped
  - 3 main contacts
    - Gate
    - Source
    - Drain
  - Gate controls current flow from Source to Drain



# Metal Oxide Semiconductor (MOS) Transistors

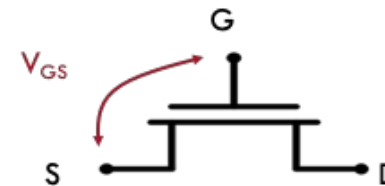
- MOS turns “on” when voltage applied across gate-source
- Voltage causes top layer of silicon to invert types, connecting S to D



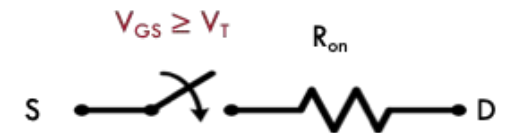
# Metal Oxide Semiconductor (MOS)

- MOS transistors are non-ideal switches
  - $0 < R_{ON} \ll R_{OFF} < \infty$
- NMOS
  - The *source* of NMOS always at *lower* voltage
  - Ideal for passing *low* voltage (0, gnd)
- PMOS
  - The *source* of PMOS always at *higher* voltage
  - Ideal for passing high voltage (1, vdd)
- The 'effective' source node can change depending on the voltage at the MOS' terminals

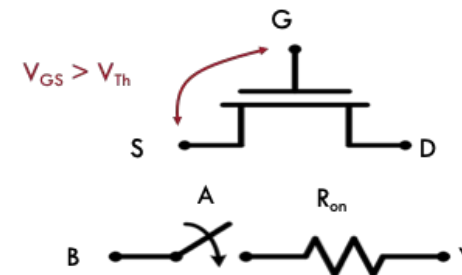
MOS Transistor



A Switch!

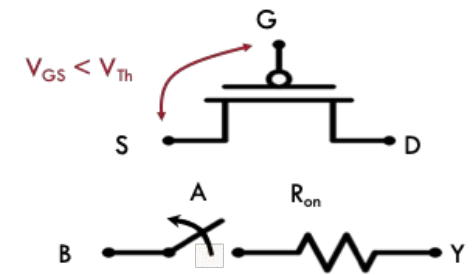


NMOS Transistor



Y = B if A = 1

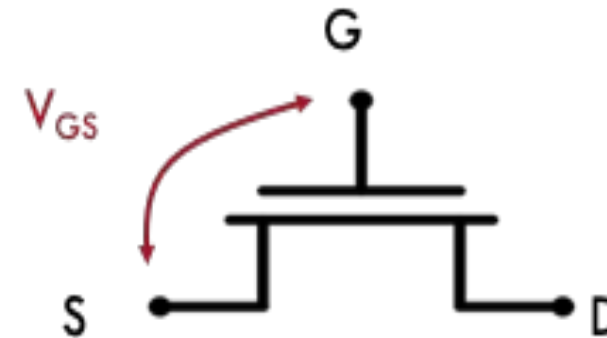
PMOS Transistor



Y = B if A = 0

# MOS

- In this class, you only need to know:
  - MOS switch model
  - On-resistance is proportional to Length/Width
  - Difference of NMOS/PMOS
  - NMOS: good for passing 0 (grounding), bad 1
  - PMOS: good for passing 1 (supply voltage), bad 0
  - Simplified parasitic capacitance ( $C_p$ ,  $C_{in}$ )

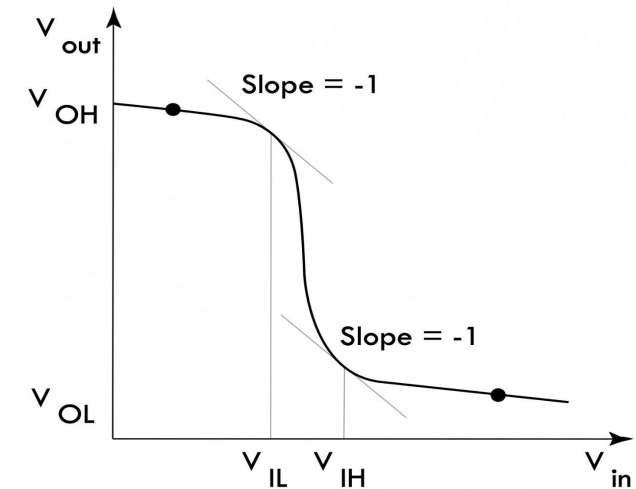
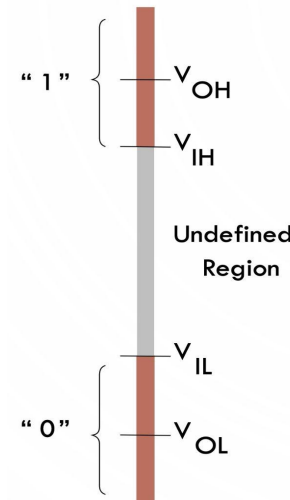
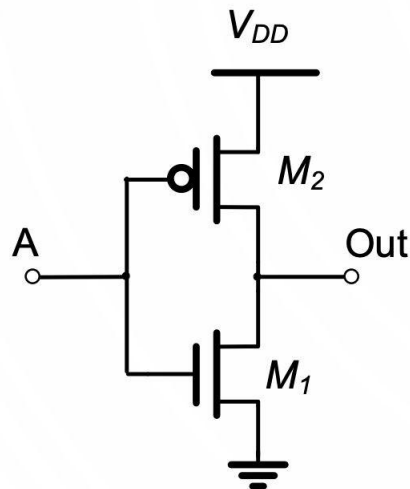
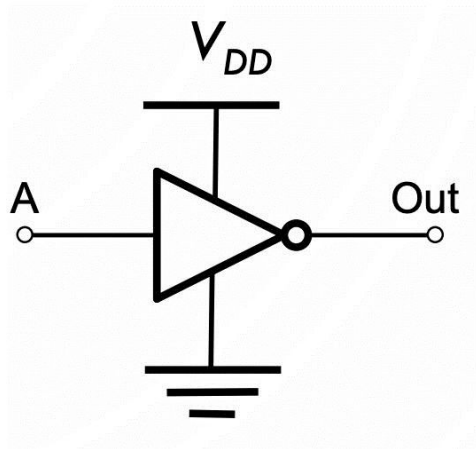


# CMOS



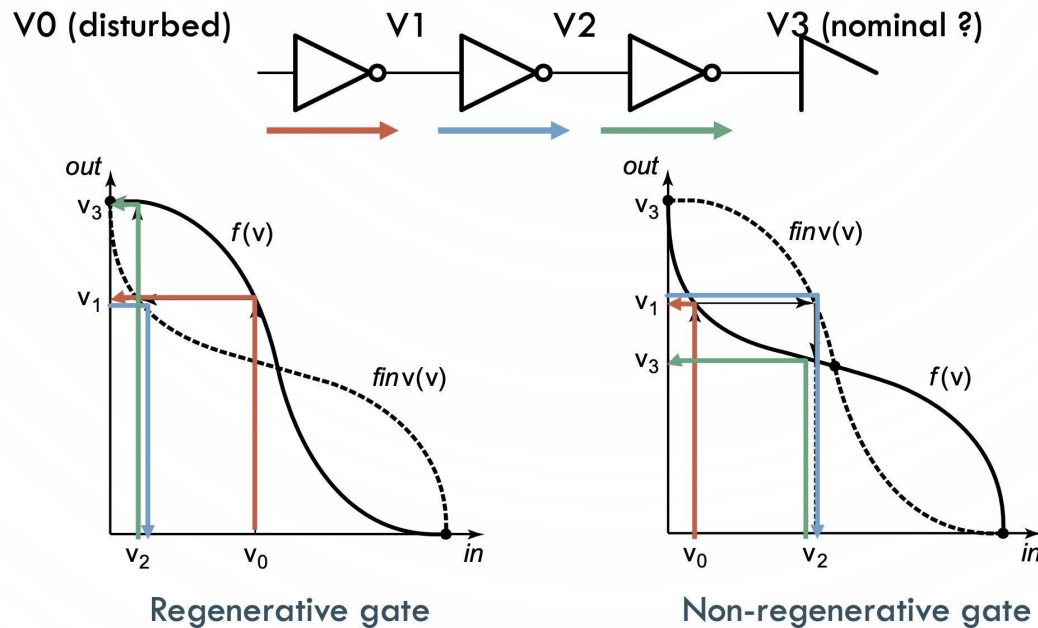
# CMOS Inverter

- Complementary Metal Oxide Semiconductor
  - Inverter has 1 NMOS and 1 PMOS
- NMOS and PMOS each have an “on” and “off” resistance
- Voltage Transfer Curve (VTC)
  - Mid/switching-point is a function of PMOS vs NMOS strength



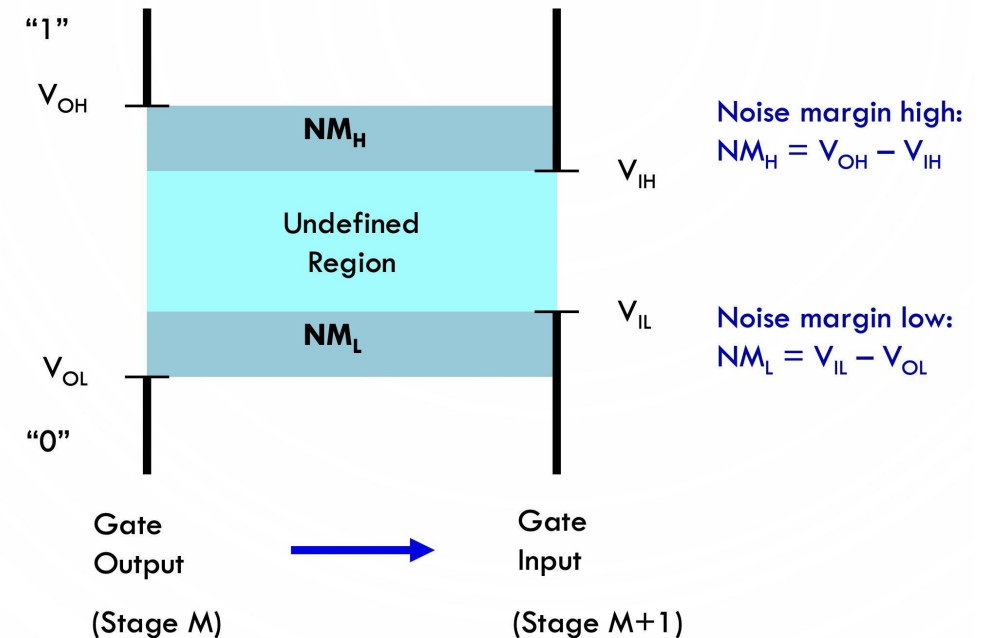
# CMOS Margins

- Noisy, but still want 1s and 0s (digital)
  - “Restoration” / “regeneration” property



- Noise margins

- The amount of noise that can be tolerated such that the signal can be correctly interpreted by the next gate
- Eg. in a chain of inverters

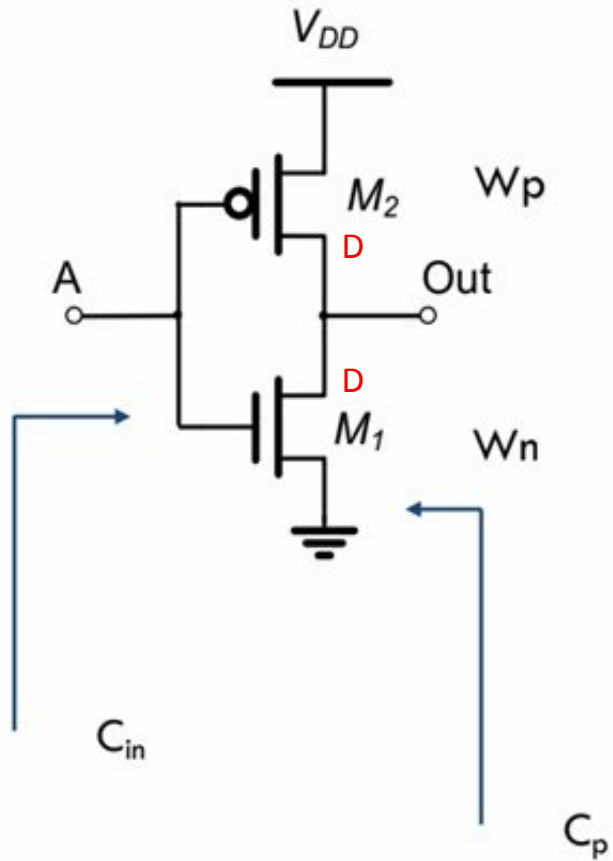


# CMOS Exercise

- Implement a NAND gate in CMOS:

# CMOS Inverters

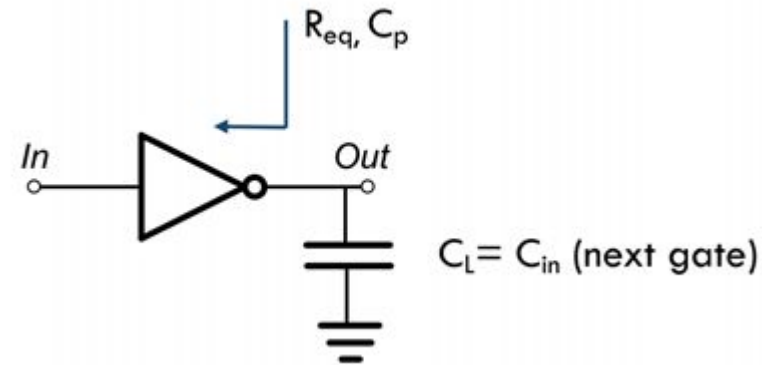
# Impact of Inverter Sizing



- $C_{in} \propto WL$ ,  $C_p \propto W$ 
  - $C_{in}$  dominated by  $C_{g,pmos} + C_{g,nmos}$
  - $C_p = \gamma C_{in}$ .  $C_p$  is dominated by  $C_{d,pmos} + C_{d,nmos}$ .  $\gamma \approx 1$ .
- $R_{eq} \propto L/W$
- Inverter usually sized for  $t_{p,LH} = t_{p,HL}$ 
  - How is  $W_p : W_n$  a function of  $\rho_p : \rho_n$ ?
- How does the RC delay change if:
  - Either  $W_p$  or  $W_n$  doubled?
  - Both  $W_p$  and  $W_n$  doubled?

# Loaded Inverter Delay

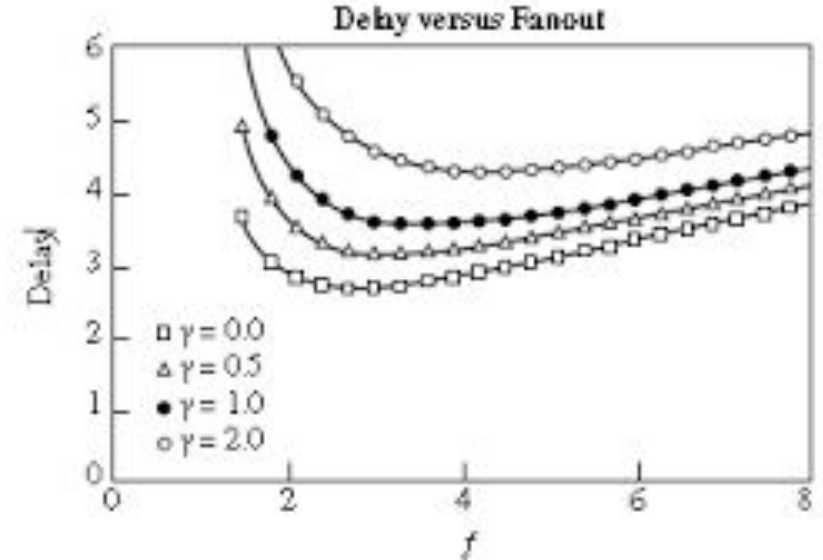
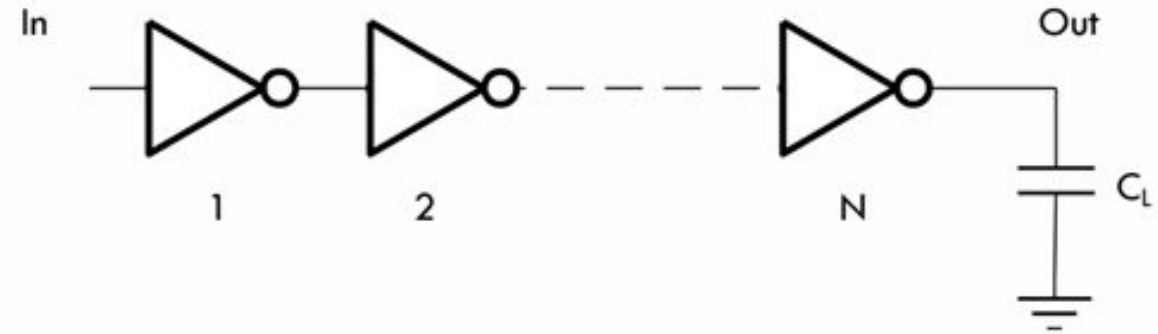
$$\begin{aligned}t_{p,inv} &= \ln 2 \cdot R_{eq} (C_{p,tot} + C_L) \\&= \ln 2 \cdot R_{eq} C_{p,tot} \left( 1 + \frac{C_L}{C_{p,tot}} \right) \\&= \ln 2 \cdot R_{eq} C_{p,tot} \left( 1 + \frac{C_L}{\gamma C_{in}} \right) \\&= \ln 2 \cdot R_{eq} C_{p,tot} \left( 1 + \frac{f}{\gamma} \right) \\&= \ln 2 \cdot \tau_{inv} \left( 1 + \frac{f}{\gamma} \right)\end{aligned}$$



- Intrinsic vs. Extrinsic delay
  - Intrinsic  $\tau_{inv}$  independent of sizing
- Fanout **f** =  $C_L / C_{in}$
- Generalizable to any CMOS gate
  -

# Inverter Chain Sizing

- Goal: minimize path delay
  - Assume 1<sup>st</sup> inverter has unit size ( $C_{in,1} = 1$ )
- Path delay  $D = t_{p1} + \dots + t_{pN} = (1 + f_1) + \dots + (1 + f_N)$
- Path fanout  $F = C_L / C_{in}$
- Solution
  - Take partial derivatives w.r.t  $C_2, \dots, C_N$
  - Get  $f_1 = f_2 = \dots = f_N$
  - Min. path delay =  $Nf + N = N \sqrt[N]{F} + N$
  - Size backwards



# Questions?